

wherein -X represents -OR², -COOH, -SO₃H, -CONHR², -COR², -SO₂NHR², -HNCONHR², or -HNCOOR²; R¹ and R², which may be the same or different, each represents a hydrogen atom, a substituted or unsubstituted, saturated or unsaturated hydrocarbon group, provided that it does not contain a radical polymerizable ethylenic double bond, a substituted or unsubstituted alicyclic hydrocarbon group, a substituted or unsubstituted aromatic hydrocarbon group, or a heterocyclic group, wherein said hydrocarbon group, alicyclic hydrocarbon group, aromatic hydrocarbon group, or the heterocyclic group may have an ether bond in the chain, provided that when -X is -OH, the R¹ represents a group other than a hydrogen atom and an aromatic hydrocarbon group, in a range of from 0.001 to 0.3% by weight based on the weight of the photosensitive resin composition components (A) to (E).

a¹
7. The photosensitive resin plate as claimed in claim 6, wherein the compound represented by the formula (I) has a boiling point of at least 95°C.

8. The photosensitive resin plate as claimed in claim 6, wherein the component (A) is at least one member selected from water-soluble polymers, alkali-soluble polymers, and alcohol-soluble polymers.

9. A photosensitive resin plate having formed thereon photocured images obtained by selectively exposing the photosensitive layer on the photosensitive resin plate as claimed in claim 6 through a mask pattern, developing, and forming the photocured images by removing the unexposed areas.--

REMARKS

Favorable reconsideration is respectfully requested.

Upon entry of the above amendment, the claims will be 6 to 9.

The above amendment is responsive to points set forth in the Official Action.

With regard to new claim 6, support is as follows: